Stamp

POSTCARD

Dr. Naoshi HIRAI ISEIM2001 Secretariat Dept. of Electrical, Electronics, and

Computer Engineering

]	]	I plan to attend the ISEIM2001 and will be accompanied by person(s).									
[	]	I intend to submit (number) paper(s) in the subject area of;									
		1	2	3	4	5					
		6	7	8	9	10					
Co	mme	ents:									

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N. Hirai (Waseda University)

### Important Addresses

### **Abstracts: Program Committee Chair**

Prof. Tatsuki Okamoto, CRIEPI E-mail: tatsuki@criepi.denken.or.jp (Abstracts should be sent via e-mails.)

### **Manuscripts: Publication Committee Chair**

Dr. Hiroyuki Nishikawa,

Department of Electrical Engineering,

Shibaura Institute of Technology,

3-9-14 Shibaura, Minato-ku, Tokyo, 108-8548, Japan (Manuscripts should be sent by regular mail or courier)

## **Inquiry: Secretary**

Dr. Naoshi Hirai, Waseda University E-mail: nhirai@mn.waseda.ac.jp (Inquiry should be sent via e-mails.)

# 2001 International Symposium on Electrical Insulating Materials (ISEIM 2001)

### and

**2001** Asian Conference on Electrical Insulation Diagnosis (ACEID2001)

# November 19 - 22, 2001

Hotel Sungarden Himeji, Himeji, Japan

# CALL FOR PAPERS

Sponsored by:

IEEJ Technical Committee on Dielectrics and Electrical Insulation

IEEE Dielectrics and Electrical Insulation Society

In cooperation with:

Korean Institute of Electrical and Electronic Material Engineers

Chinese Electrotechnical Society

Kansai Section of IEEJ

IEEJ Investigation Committee on Insulation Lifetime of Dielectric Materials and Electrical Apparatus

Himeji Institute of Technology





### Invitation

ISEIM2001 at Himeji, Japan will be held on Nov. 19-22, 2001. The previous conferences were held in Tokyo, Japan (1995) and Toyohashi, Japan (1998). The organizing committee cordially invites you to participate in the conference.

### About Himeji

A city of 460,000 people, Himeji is located in the heart of the Himeji plain in the southwestern part of Hyogo Prefecture. Progressively amalgamating adjacent towns and villages since its municipal inauguration in 1889, Himeji now stretches 23.5 km to the east and west 21.3 km to the north and south and boasts a total area of 273 square kilometers. Himeji is said to have been populated by human beings for about 10,000 years, a notion supported by the discovery of ancient artifacts throughout the city. Himeji Castle and Horyu-ji Buddhist Temple in Nara were given the World Cultural Heritage status for the first time in Japan, by the World Heritage Committee of UNESCO in 1993. The huge plain including Himeji flourished over the years as an industry and transportation center in proximity to the cities of Kyoto, Osaka and Kobe.

### **Main Topics**

- 1. Electrical Conduction and Breakdown in Dielectrics
- 2. Space Charge, Surface and Interfacial Phenomena
- 3. Electrical Insulation for Apparatus and Cables
- 4. Aging and Degradation, their Detection and Monitoring
- 5. Test and Measurement Techniques
- 6. Insulation Design and Reliability
- 7. Eco-friendly Dielectric Materials and Recycling
- 8. Dielectric Materials for Electronics
- 9. New and Functional Dielectric Materials
- 10. Dielectric Phenomena and Their Applications

Papers on the following topics are particularly welcome: polymeric insulators and outdoor insulation, space charge measurements, on-line monitoring and diagnostics of power apparatus, GIS and cables, diagnosis of GIS, DC cables, development of polymeric cables and joints for higher electric fields, organic and inorganic thin films, new and functional materials including biological and medical dielectrics, and ferroelectric materials.

### **Technical Visits**

The following technical visits to local industries will be arranged in the afternoon of November 21 (Wed).

- A: Japan Synchrotron Radiation Research Institute (SPring-8)
- **B:** Kansai Advanced Research Center, Communications Research Laboratory
- C: Mitsubishi Electric Corporation, Ako Works for Large Transformers

### Language

The working language of the symposium is English. All printed matter will appear in English.

### **Submission of Papers**

You are invited to submit an abstract of not more than 200 words to the Program Committee Chair preferably via e-mail by March 20, 2001. The abstract should include title, author's name(s) and affiliation(s) and the mailing and e-mail addresses, phone and fax numbers of the corresponding author. Acceptance or rejection notices will be mailed by the end of May 2001 to the corresponding authors. The authors of accepted papers will be requested to submit camera-ready manuscripts by July 31, 2001 to Publication Committee Chair. Accepted papers will be published in the Symposium Proceedings.

### Registration

Registration fee including banquet fee is ¥35,000 (Japanese yen) for members of IEEJ, IEEE, CES, or KIEEME, ¥40,000 for non-members, and ¥15,000 for students with valid IDs.

### **Accommodations**

Conference special room rates including breakfast, service and taxes are \(\frac{\pmax}{8}\),500 for single and \(\frac{\pmax}{16}\),000 for double rooms. The hotel reservation should be sent by fax (+81-78-391-3983) or e-mail (danryokobe\_ec@kns.jtb.co.jp) to the Japan Travel Bureau (JTB) by the *end of September 2001* using the hotel reservation form.

### **ISEIM 2001 WWW Site**

More information about ISEIM2001 is available at the following web site:

http://www.waseda.ac.jp/conference/ISEIM 2001/index.html

### PLEASE KEEP IN MIND

**Important Dates** 

Abstract Due: March 20, 2001 Manuscript Due: July 31, 2001

Conference Dates: November 19 - 22, 2001

# 2001 International Symposium on Electrical Insulating Materials

To the Secretariat of ISEIM2001(nhirai@mn.waseda.ac.jp)

Dear Sir :

I am sending you, without obligation, my name and correspondence address and ask for keeping me informed about future developments in the organization of ISEIM2001

ISEIM20	uture 01.	develo	pments	ın	the	organization	О
Prof.	Dr.	Mr.	Ms.				
Family n	ame (P	Please pr	int)				
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